

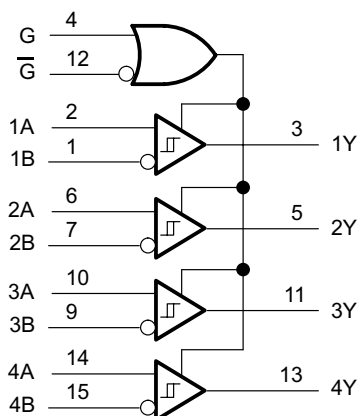
AM26LS32Ax、AM26LS33Ax クワッド差動ライン・レシーバ

1 特長

- AM26LS32A デバイスは、ANSI TIA/EIA-422-B、TIA/EIA-423-B、ITU 勧告 V.10 および V.11 の要件を満たす、または上回ります
- AM26LS32A デバイスは同相範囲が $\pm 7V$ で、感度が $\pm 200mV$ です
- AM26LS33A デバイスは同相範囲が $\pm 15V$ で、感度が $\pm 500mV$ です
- 入力ヒステリシス: 50mV (標準値)
- 単一の 5V 電源で動作
- 低消費電力ショットキー回路
- 3 ステート出力
- 相補出力のイネーブル入力
- 入力インピーダンス: 12k Ω (最小値)
- オープン入力フェイルセーフ

2 アプリケーション

- 高信頼性車載用アプリケーション
- ファクトリ・オートメーション
- ATM およびキャッシュ・カウンタ
- スマート・グリッド
- AC およびサーボ・モータ・ドライブ



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ピン番号は D、N、NS、PW パッケージのみのものです。

論理図 (正論理)

3 概要

AM26LS32Ax および AM26LS33Ax デバイスは、平衡および不平衡のデジタル・データ転送用のクワッド差動ライン・レシーバです。イネーブル機能は 4 つのレシーバすべてに共通で、アクティブ High またはアクティブ Low の入力から選択できます。3 ステート出力により、バス構成システムに直接接続できます。入力がオープン的时候、フェイルセーフ設計により出力が常に High であることが保証されます。

AM26LS32 や AM26LS33 と比較すると、AM26LS32A と AM26LS33A には感度を向上させるため追加の増幅段が組み込まれています。入力インピーダンスが増加し、その結果、バス・ラインの負荷が減少します。段を追加すると伝搬遅延が長くなりますが、ほとんどのアプリケーションでは交換可能性には影響しません。

AM26LS32AC および AM26LS33AC は 0°C ~ 70°C での動作が規定されています。AM26LS32AI は -40°C ~ 85°C での動作が規定されています。AM26LS32AM および AM26LS33AM は防衛用温度範囲 -55°C ~ 125°C での動作が規定されています。

パッケージ情報

部品番号	パッケージ (1)	パッケージ・サイズ (2)
AM26LS3xAC	PDIP (16)	19.3mm × 9.4mm
AM26LS32AI	SOIC (16)	9.9mm × 6mm
AM26LS32AC	SO (16)	10.2mm × 7.8mm
	TSSOP (16)	5mm × 6.4mm
AM26LS3xAM	CDIP (16)	19.56mm × 6.92mm
	LCCC (20)	8.9mm × 8.9mm

- 利用可能なすべてのパッケージについては、データシートの末尾にある注文情報を参照してください。
- パッケージ・サイズ (長さ × 幅) は公称値であり、該当する場合はピンも含まれます。



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4 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision F (August 2016) to Revision G (August 2023)	Page
• 「製品情報」表を「パッケージ情報」表に変更	1
• Changed the <i>Thermal Information</i> table.....	5
• Changed the <i>Typical Characteristics</i>	8

Changes from Revision E (October 2007) to Revision F (August 2016)	Page
• 「アプリケーション」セクション、「ESD 定格」表、「機能説明」セクション、「デバイスの機能モード」、「アプリケーションと実装」セクション、「電源に関する推奨事項」セクション、「レイアウト」セクション、「デバイスおよびドキュメントのサポート」セクション、「メカニカル、パッケージ、および注文情報」セクションを追加	1
• Changed R _{θJA} values in the <i>Thermal Information</i> table: 73 to 75.7 for (D), 67 to 45.3 (N), 64 to 75.8 (NS), and 108 to 102.7 (PW).....	5

5 Pin Configuration and Functions

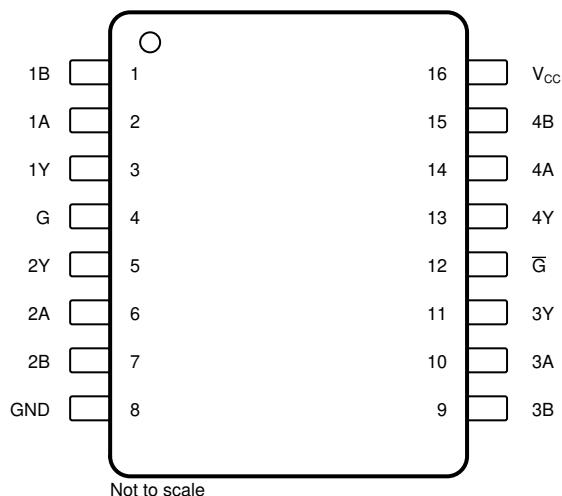
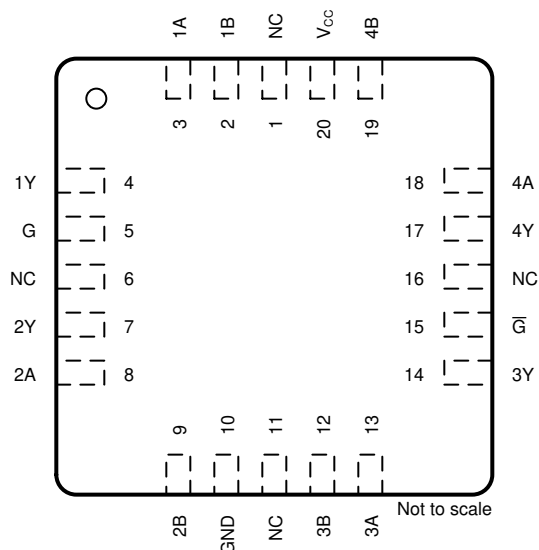


FIG 5-1. D, J, N, NS, and PW Package 16-Pin SOIC, CDIP, PDIP, SO, and TSSOP (Top View)



NC - No internal connection

FIG 5-2. FK Package, 20-Pin LCCC (Top View)

NAME	PIN		TYPE	DESCRIPTION
	SOIC, CDIP, PDIP, SO, TSSOP	LCCC		
1A	2	3	I	RS422/RS485 differential input (noninverting)
1B	1	2	I	RS422/RS485 differential input (inverting)
1Y	3	4	O	Logic level output
2A	6	8	I	RS422/RS485 differential input (noninverting)
2B	7	9	I	RS422/RS485 differential input (inverting)
2Y	5	7	O	Logic level output
3A	10	13	I	RS422/RS485 differential input (noninverting)
3B	9	12	I	RS422/RS485 differential input (inverting)
3Y	11	14	O	Logic level output
4A	14	18	I	RS422/RS485 differential input (noninverting)
4B	15	19	I	RS422/RS485 differential input (inverting)
4Y	13	17	O	Logic level output
$\bar{G}$	12	15	I	Active-Low select
G	4	5	I	Active-High select
GND	8	10	—	Ground
NC	—	1, 6, 11, 16	—	No internal connection
V _{CC}	16	20	—	Power supply

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
Supply voltage, V_{CC} ⁽²⁾			7	V
Input voltage, V_I	Any differential input		±25	V
	Other inputs		7	
Differential input voltage, V_{ID} ⁽³⁾			±25	V
Continuous total power dissipation		See セクション 6.7		
Case temperature, T_C , FK package (60 s)			260	°C
Lead temperature ⁽⁴⁾	D or N package (10 s)		260	°C
	J package (60 s)		300	
Storage temperature, T_{stg}		–65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential voltages, are with respect to the network ground terminal.
- (3) Differential voltage values are at the noninverting (A) input terminals with respect to the inverting (B) input terminals.
- (4) 1.6 mm (1/16 inch) from case

6.2 ESD Ratings

		VALUE	UNIT
$V_{(ESD)}$ Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±500	V
	Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±2000	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

			MIN	NOM	MAX	UNIT
V_{CC} Supply voltage	AM26LS32AC, AM26LS32AI, AM26LS33AC		4.75	5	5.25	V
	AM26LS32AM, AM26LS33AM		4.5	5	5.5	
V_{IH} High-level input voltage			2			V
V_{IL} Low-level input voltage					0.8	V
V_{IC} Common-mode input voltage	AM26LS32A				±7	V
	AM26LS33A				±15	
I_{OH} High-level output current					–440	μA
I_{OL} Low-level output current					8	mA
T_A Operating free-air temperature	AM26LS32AC, AM26LS33AC		0		70	°C
	AM26LS32AI		–40		85	
	AM26LS32AM, AM26LS33AM		–55		125	

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾	AM26LS3xAC, AM26LS32AI				AM26LS32AC				UNIT
	D (SOIC)	DR (SOIC-Reel)	N (PDIP)	NR (PDIP-Reel)	NS (SO)	NSR (SO-Reel)	PW (TSSOP)	PWR (TSSOP-Reel)	
	16 PINS	16 PINS	16 PINS	16 PINS	16 PINS	16 PINS	16 PINS	16 PINS	
$R_{\theta JA}$ Junction-to-ambient thermal resistance	75.7	84.6	45.3	60.6	75.8	88.5	102.7	107.5	°C/W
$R_{\theta JC(top)}$ Junction-to-case (top) thermal resistance	35	43.5	32.7	48.1	32.9	46.2	37.8	38.4	°C/W
$R_{\theta JB}$ Junction-to-board thermal resistance	33.3	43.2	25.3	40.6	36.6	50.7	47.7	53.7	°C/W
Ψ_{JT} Junction-to-top characterization parameter	6.6	10.4	17.8	27.5	6	13.5	3	3.2	°C/W
Ψ_{JB} Junction-to-board characterization parameter	33	42.8	25.1	40.3	36.3	50.3	47.1	53.1	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

6.5 Electrical Characteristics

over recommended ranges of V_{CC} , V_{IC} , and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP ⁽¹⁾	MAX	UNIT
V_{IT+}	Positive-going input threshold voltage	$V_O = V_{OHmin}$, $I_{OH} = -440 \mu A$	AM26LS32A			0.2	V
			AM26LS33A			0.5	
V_{IT-}	Negative-going input threshold voltage	$V_O = 0.45 V$, $I_{OL} = 8 mA$	AM26LS32A	-0.2 ⁽²⁾			V
			AM26LS33A	-0.5 ⁽²⁾			
V_{hys}	Hysteresis voltage ($V_{IT+} - V_{IT-}$)				50		mV
V_{IK}	Enable-input clamp voltage	$V_{CC} = MIN$, $I_I = -18 mA$				-1.5	V
V_{OH}	High-level output voltage	$V_{CC} = MIN$, $V_{ID} = 1 V$, $V_{I(G)} = 0.8 V$, $I_{OH} = -440 \mu A$	AM26LS32AC, AM26LS33AC		2.7		V
			AM26LS32AM, AM26LS32AI, AM26LS33AM		2.5		
V_{OL}	Low-level output voltage	$V_{CC} = MIN$, $V_{ID} = -1 V$, $V_{I(G)} = 0.8 V$	$I_{OL} = 4 mA$			0.4	V
			$I_{OL} = 8 mA$			0.45	
I_{OZ}	Off-state (high-impedance state) output current	$V_{CC} = MAX$	$V_O = 2.4 V$			20	μA
			$V_O = 0.4 V$			-20	
I_I	Line input current	$V_I = 15 V$, other input at $-10 V$ to $15 V$				1.2	mA
		$V_I = -15 V$, other input at $-15 V$ to $10 V$				-1.7	
$I_{I(EN)}$	Enable input current	$V_I = 5.5 V$				100	μA
I_H	High-level enable current	$V_I = 2.7 V$				20	μA
I_L	Low-level enable current	$V_I = 0.4 V$				-0.36	mA
r_i	Input resistance	$V_{IC} = -15 V$ to $15 V$, one input to ac ground		12	15		k Ω
I_{OS}	Short-circuit output current ⁽³⁾	$V_{CC} = MAX$		-15		-85	mA
I_{CC}	Supply current	$V_{CC} = MAX$, all outputs disabled			52	70	mA

(1) All typical values are at $V_{CC} = 5 V$, $T_A = 25^\circ C$, and $V_{IC} = 0$.

(2) The algebraic convention, in which the less positive (more negative) limit is designated as minimum, is used in this data sheet for threshold levels only.

(3) Not more than one output must be shorted to ground at a time, and duration of the short circuit must not exceed one second.

6.6 Switching Characteristics

$C_L = 15 \text{ pF}$, $V_{CC} = 5 \text{ V}$, and $T_A = 25^\circ\text{C}$ (see [セクション 7](#); unless otherwise noted)

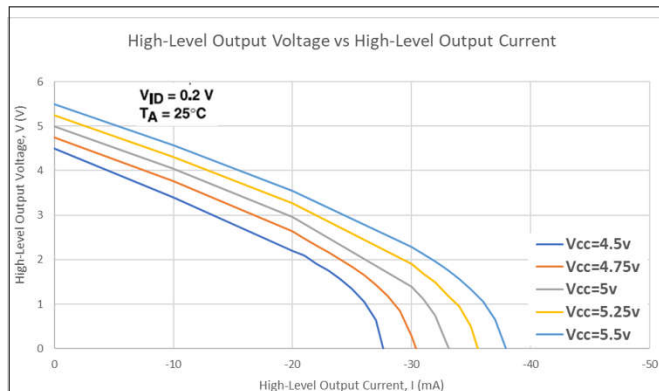
PARAMETER		MIN	TYP ⁽¹⁾	MAX	UNIT
t_{PLH}	Propagation delay time, low-to-high-level output		20	35	ns
t_{PHL}	Propagation delay time, high-to-low-level output		22	35	ns
t_{PZH}	Output enable time to high level		17	22	ns
t_{PZL}	Output enable time to low level		20	25	ns
t_{PHZ}	Output disable time from high level		21	30	ns
t_{PLZ}	Output disable time from low level		30	40	ns

(1) All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$, and $V_{IC} = 0$.

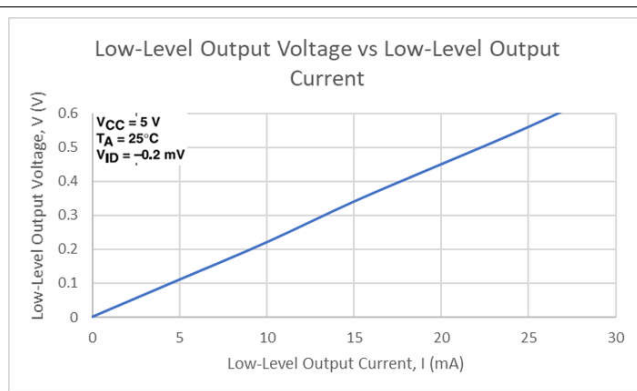
6.7 Dissipation Ratings

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATION FACTOR ABOVE $T_A = 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING	$T_A = 125^\circ\text{C}$ POWER RATING
FK	1375 mW	11 mW/ $^\circ\text{C}$	880 mW	275 mW
J	1375 mW	11 mW/ $^\circ\text{C}$	880 mW	275 mW

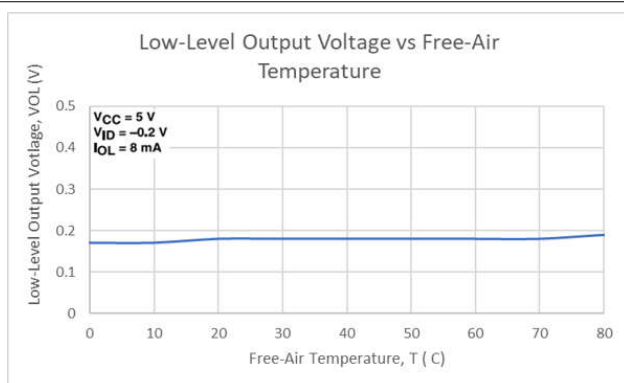
6.8 Typical Characteristics



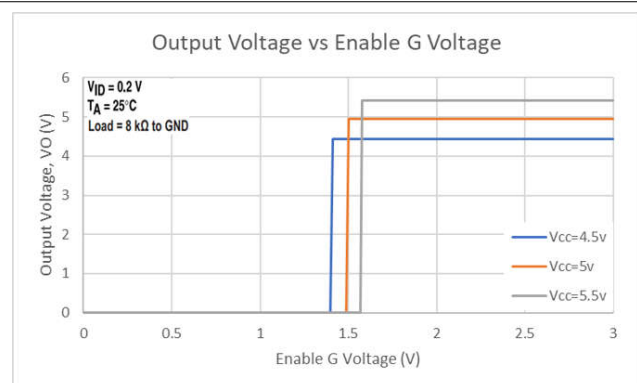
6-1. High-Level Output Voltage vs High-Level Output Current



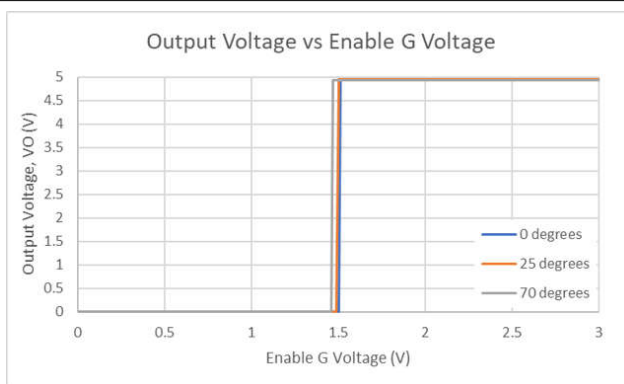
6-2. Low-Level Output Voltage vs Low-Level Output Current



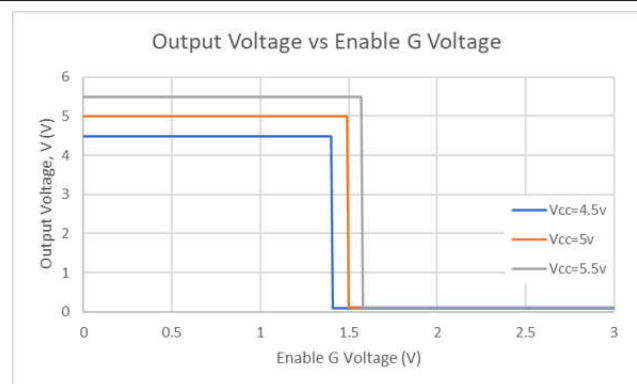
6-3. Low-Level Output Voltage vs Free-Air Temperature



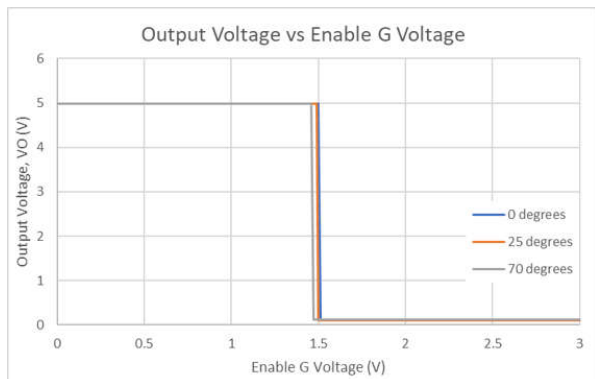
6-4. Output Voltage vs Enable G Voltage



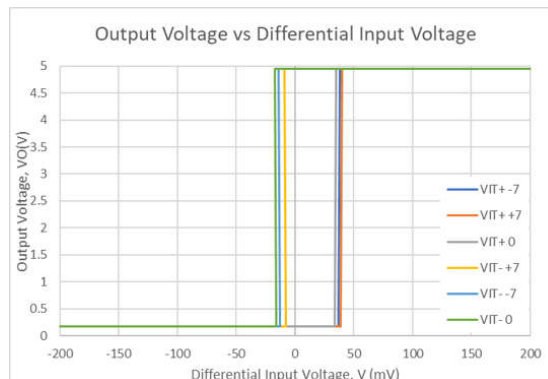
6-5. Output Voltage vs Enable G Voltage



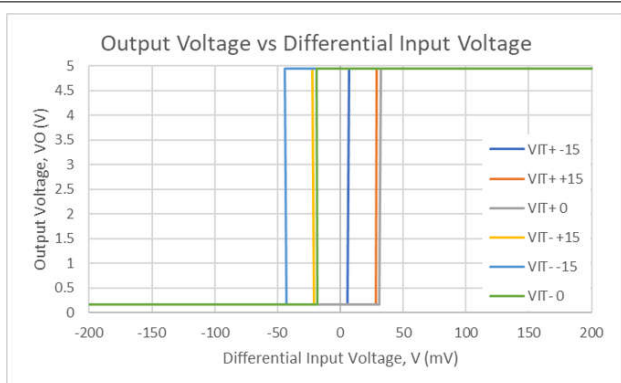
6-6. Output Voltage vs Enable G Voltage



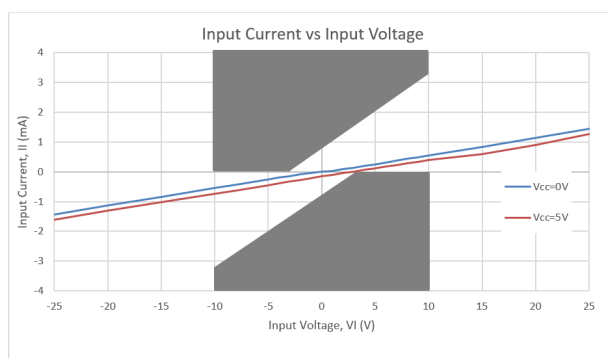
6-7. Output Voltage vs Enable G Voltage



6-8. AM26LS32A Output Voltage vs Differential Input Voltage



6-9. AM26LS33A Output Voltage vs Differential Input Voltage



The unshaded area shows requirements of paragraph 4.2.1 of ANSI Standards EIA/TIA-422-B and EIA/TIA-423-B.

6-10. Input Current vs Input Voltage

7 Parameter Measurement Information

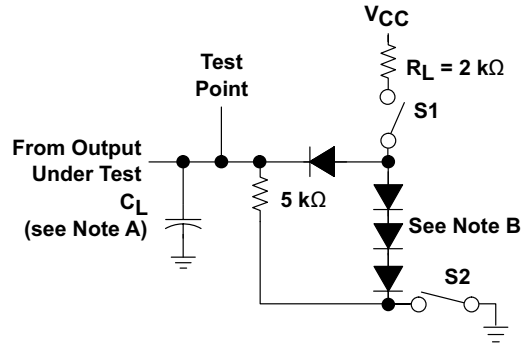


图 7-1. Test Circuit

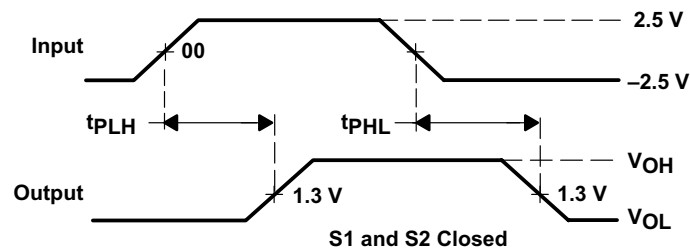


Figure 7-2. Voltage Waveforms For t_{PLH} , t_{PHL}

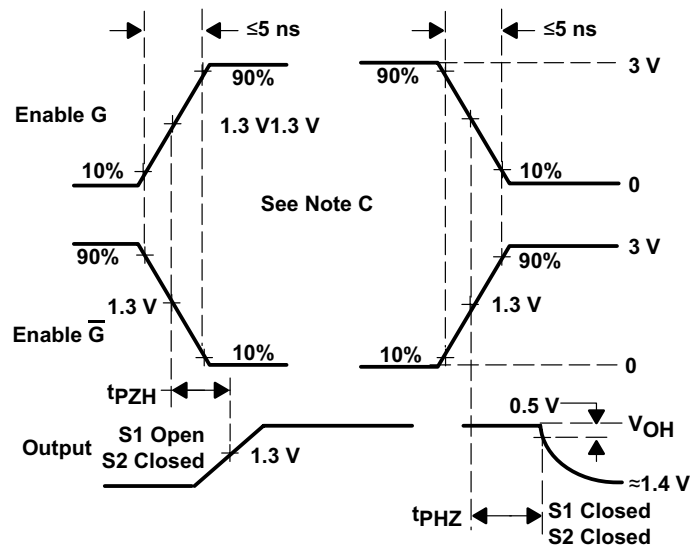
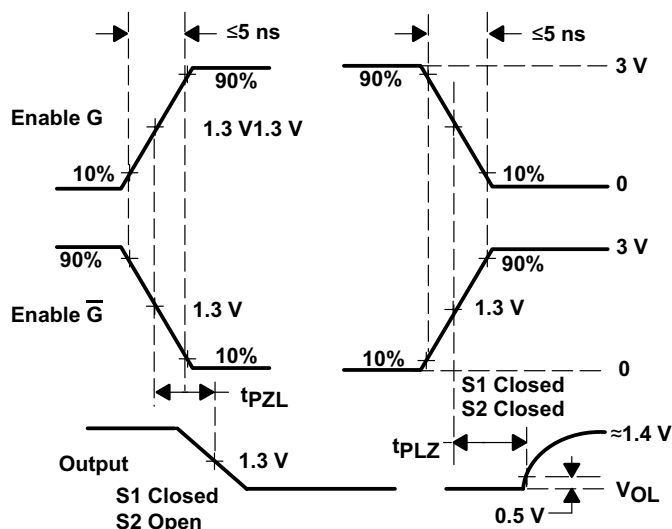
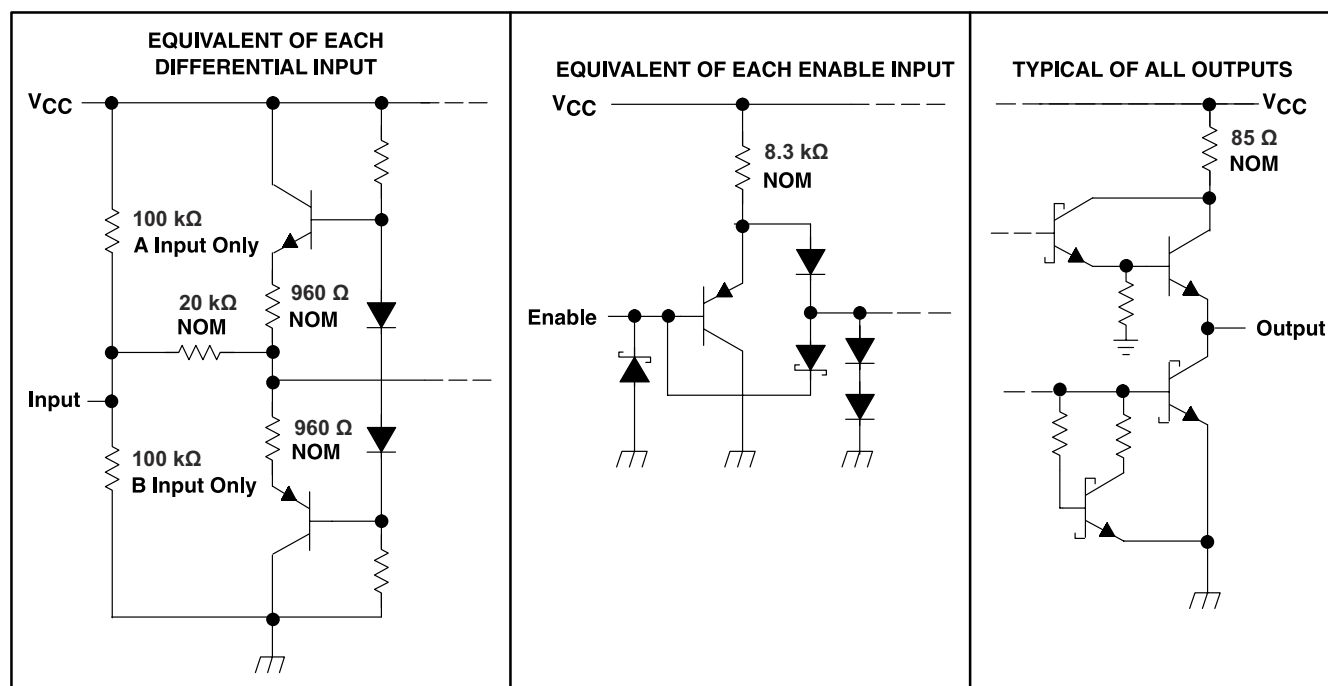


Figure 7-3. Voltage Waveforms For t_{PHZ} , t_{PZH}



- A. CL includes probe and jig capacitance.
- B. All diodes are 1N3064 or equivalent.
- C. Enable G is tested with $\bar{G}$ high, $\bar{G}$ is tested with G low.

7-4. Voltage Waveforms For t_{PLZ} , t_{PZL}



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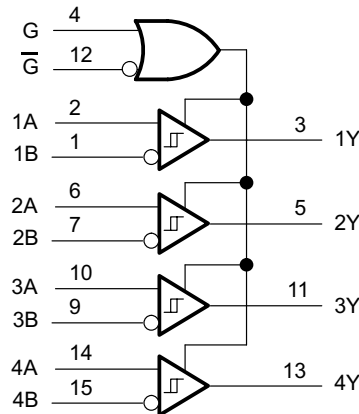
7-5. Schematics of Inputs and Outputs

8 Detailed Description

8.1 Overview

The AM26LS32 is a quadruple-differential line receiver that meets the necessary requirements for NSI TIA/EIA-422-B, TIA/EIA-423-B, and ITU Recommendation V.10 and V.11. This device allows a low-power or low-voltage MCU to interface with heavy machinery, subsystems, and other devices through long wires of up to 1000 m, giving any design a reliable and easy-to-use connection. As any RS422 interface, the AM26LS32 works in a differential voltage range, which enables very good signal integrity.

8.2 Functional Block Diagram



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 8-1. Logic Diagram (Positive Logic)

8.3 Feature Description

The device can be configured using the G and $\overline{G}$ logic inputs to select receiver output. The high voltage or logic 1 on the G pin allows the device to operate on an active-high, and having a low voltage or logic 0 on the G enables active low operation. These are simple ways to configure the logic to match that of the receiving or transmitting controller or microprocessor.

8.4 Device Functional Modes

The receivers implemented in these RS422 devices can be configured using the G and $\overline{G}$ logic pins to be enabled or disabled. This allows users to ignore or filter out transmissions as desired.

表 8-1. Function Table, Each Receiver

DIFFERENTIAL A–B	ENABLES ⁽¹⁾		OUTPUT ⁽¹⁾ Y
	G	$\overline{G}$	
$V_{ID} \geq V_{IT+}$	H	X	H
	X	L	H
$V_{IT-} \leq V_{ID} \leq V_{IT+}$	H	X	?
	X	L	?
$V_{ID} \leq V_{IT-}$	H	X	L
	X	L	L
X	L	H	Z
Open	H	X	H
	X	L	H

(1) H = High level, L = Low level, X = Irrelevant, Z = High impedance (off), ? = Indeterminate

9.2.3 Application Curve

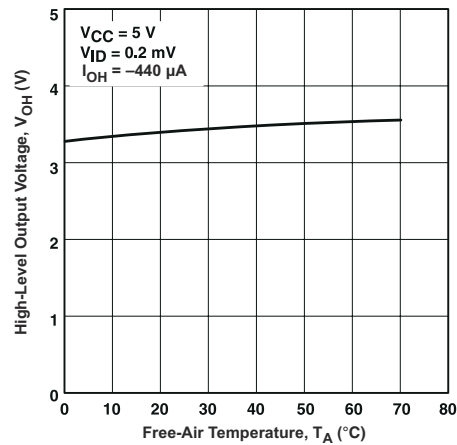


FIG 9-2. High-Level Output Voltage vs Free-Air Temperature

9.3 Power Supply Recommendations

Place 0.1-μF bypass capacitors close to the power-supply pins to reduce errors coupling in from noisy or high-impedance power supplies.

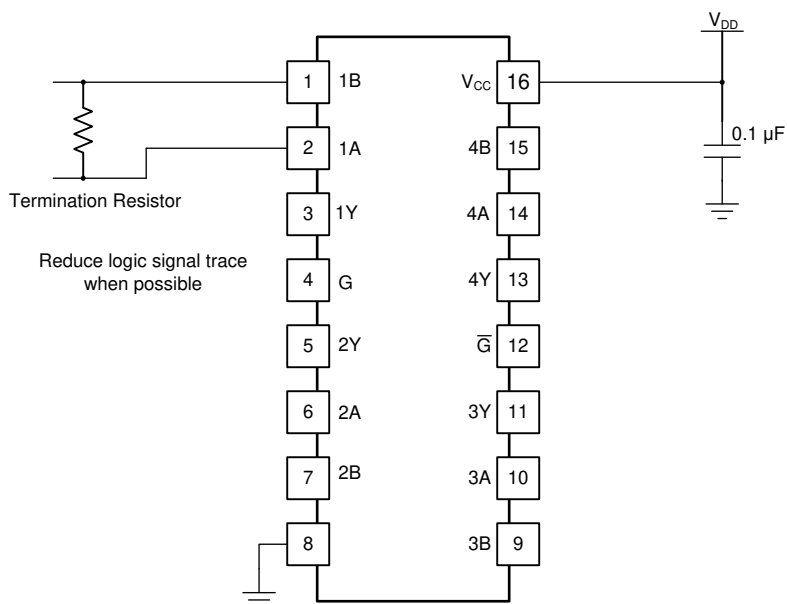
9.4 Layout

9.4.1 Layout Guidelines

For best operational performance of the device, use good PCB layout practices including:

- Noise can propagate into analog circuitry through the power pins of the circuit as a whole, as well as the operational amplifier. Bypass capacitors are used to reduce the coupled noise by providing low impedance power sources local to the analog circuitry.
- Connect low-ESR, 0.1-μF ceramic bypass capacitors between each supply pin and ground, placed as close to the device as possible. A single bypass capacitor from V+ to ground is applicable for single supply applications.
- Separate grounding for analog and digital portions of circuitry is one of the simplest and most-effective methods of noise suppression. One or more layers on multilayer PCBs are usually devoted to ground planes. A ground plane helps distribute heat and reduces EMI noise pickup. Make sure to physically separate digital and analog grounds, paying attention to the flow of the ground current.
- To reduce parasitic coupling, run the input traces as far away from the supply or output traces as possible. If it is not possible to keep them separate, it is much better to cross the sensitive trace perpendicular as opposed to in parallel with the noisy trace.
- Place the external components as close to the device as possible. Keeping RF and RG close to the inverting input minimizes parasitic capacitance.
- Keep the length of input traces as short as possible. Always remember that the input traces are the most sensitive part of the circuit.
- Consider a driven, low-impedance guard ring around the critical traces. A guard ring can significantly reduce leakage currents from nearby traces that are at different potentials.

9.4.2 Layout Example



✎ 9-3. Layout with PCB Recommendations

10 Device and Documentation Support

10.1 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、ti.com のデバイス製品フォルダを開いてください。「更新の通知を受け取る」をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取れます。変更の詳細については、修正されたドキュメントに含まれている改訂履歴をご覧ください。

10.2 サポート・リソース

TI E2E™ サポート・フォーラムは、エンジニアが検証済みの回答と設計に関するヒントをエキスパートから迅速かつ直接得ることができる場所です。既存の回答を検索したり、独自の質問をしたりすることで、設計に必要な支援を迅速に得ることができます。

リンクされているコンテンツは、該当する貢献者により、現状のまま提供されるものです。これらは TI の仕様を構成するものではなく、必ずしも TI の見解を反映したものではありません。TI の[使用条件](#)を参照してください。

10.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

すべての商標は、それぞれの所有者に帰属します。

10.4 静電気放電に関する注意事項



この IC は、ESD によって破損する可能性があります。テキサス・インスツルメンツは、IC を取り扱う際には常に適切な注意を払うことを推奨します。正しい取り扱いおよび設置手順に従わない場合、デバイスを破損するおそれがあります。

ESD による破損は、わずかな性能低下からデバイスの完全な故障まで多岐にわたります。精密な IC の場合、パラメータがわずかに変化するだけで公表されている仕様から外れる可能性があるため、破損が発生しやすくなっています。

10.5 用語集

[テキサス・インスツルメンツ用語集](#) この用語集には、用語や略語の一覧および定義が記載されています。

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-7802003M2A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 7802003M2A AM26LS 32AMFKB
5962-7802003MEA	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-7802003ME A AM26LS32AMJB
5962-7802003MFA	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-7802003MF A AM26LS32AMWB
5962-7802004M2A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 7802004M2A AM26LS 33AMFKB
5962-7802004MEA	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-7802004ME A AM26LS33AMJB
5962-7802004MFA	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-7802004MF A AM26LS33AMWB
AM26LS32ACD	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	0 to 70	26LS32AC
AM26LS32ACDR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	26LS32AC
AM26LS32ACDR.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	26LS32AC
AM26LS32ACDRE4	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	26LS32AC
AM26LS32ACDRG4	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	26LS32AC
AM26LS32ACN	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	AM26LS32ACN
AM26LS32ACN.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	AM26LS32ACN
AM26LS32ACNG4	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	AM26LS32ACN
AM26LS32ACNG4.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	AM26LS32ACN
AM26LS32ACNSR	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	26LS32A
AM26LS32ACNSR.A	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	26LS32A
AM26LS32ACNSRG4	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	26LS32A
AM26LS32ACPW	Obsolete	Production	TSSOP (PW) 16	-	-	Call TI	Call TI	0 to 70	SA32A

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
AM26LS32ACPWR	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	SA32A
AM26LS32ACPWR.A	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	SA32A
AM26LS32ACPWRE4	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	SA32A
AM26LS32AID	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	-40 to 85	26LS32AI
AM26LS32AIDR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	26LS32AI
AM26LS32AIDR.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	26LS32AI
AM26LS32AIDRG4	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	26LS32AI
AM26LS32AIN	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	AM26LS32AIN
AM26LS32AIN.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	AM26LS32AIN
AM26LS32AMFKB	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-7802003M2A AM26LS32AMFKB
AM26LS32AMFKB.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-7802003M2A AM26LS32AMFKB
AM26LS32AMJ	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	AM26LS32AMJ
AM26LS32AMJ.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	AM26LS32AMJ
AM26LS32AMJB	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-7802003MEA AM26LS32AMJB
AM26LS32AMJB.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-7802003MEA AM26LS32AMJB
AM26LS32AMWB	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-7802003MFA AM26LS32AMWB
AM26LS32AMWB.A	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-7802003MFA AM26LS32AMWB
AM26LS33ACD	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	0 to 70	26LS33AC
AM26LS33ACDR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	26LS33AC
AM26LS33ACDR.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	26LS33AC

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
AM26LS33ACN	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	AM26LS33ACN
AM26LS33ACN.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	AM26LS33ACN
AM26LS33AMFKB	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-7802004M2A AM26LS33AMFKB
AM26LS33AMFKB.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-7802004M2A AM26LS33AMFKB
AM26LS33AMJ	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	AM26LS33AMJ
AM26LS33AMJ.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	AM26LS33AMJ
AM26LS33AMJB	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-7802004ME A AM26LS33AMJB
AM26LS33AMJB.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-7802004ME A AM26LS33AMJB
AM26LS33AMWB	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-7802004MF A AM26LS33AMWB
AM26LS33AMWB.A	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-7802004MF A AM26LS33AMWB

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF AM26LS32A, AM26LS32AM, AM26LS33A, AM26LS33AM :

- Catalog : [AM26LS32A](#), [AM26LS33A](#)
- Military : [AM26LS32AM](#), [AM26LS33AM](#)
- Space : [AM26LS33A-SP](#), [AM26LS33A-SP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

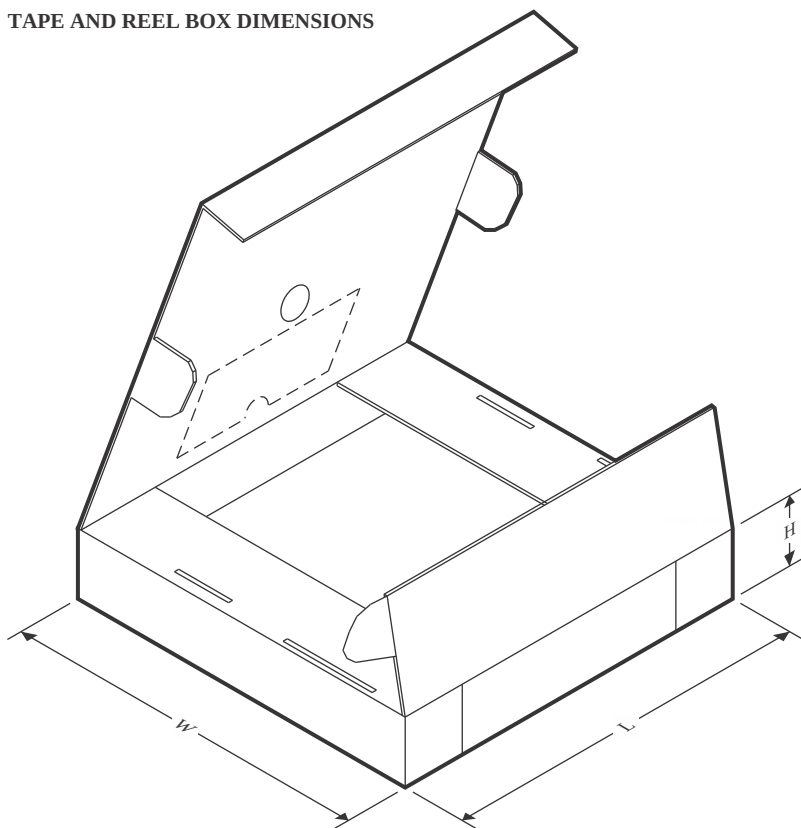
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
AM26LS32ACDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
AM26LS32ACNSR	SOP	NS	16	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
AM26LS32ACPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
AM26LS32AIDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
AM26LS33ACDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

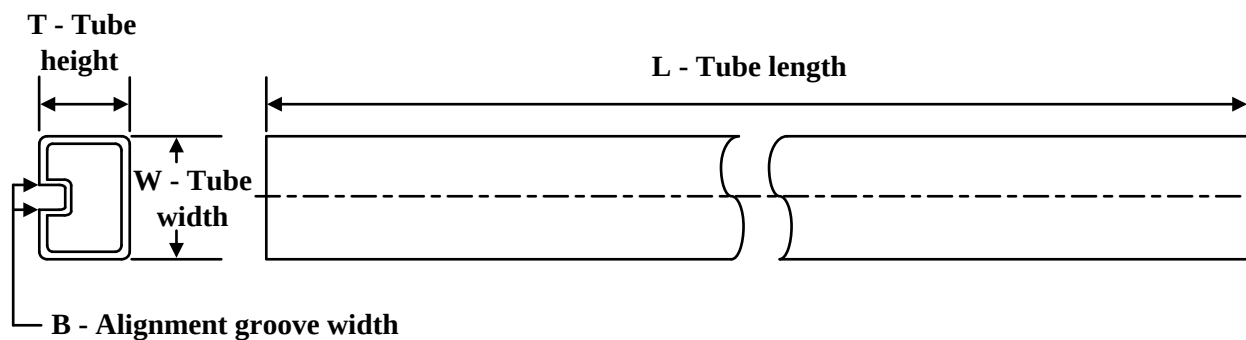
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

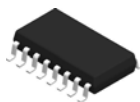
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
AM26LS32ACDR	SOIC	D	16	2500	353.0	353.0	32.0
AM26LS32ACNSR	SOP	NS	16	2000	353.0	353.0	32.0
AM26LS32ACPWR	TSSOP	PW	16	2000	353.0	353.0	32.0
AM26LS32AIDR	SOIC	D	16	2500	340.5	336.1	32.0
AM26LS33ACDR	SOIC	D	16	2500	340.5	336.1	32.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-7802003M2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-7802003MFA	W	CFP	16	25	506.98	26.16	6220	NA
5962-7802004M2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-7802004MFA	W	CFP	16	25	506.98	26.16	6220	NA
AM26LS32ACN	N	PDIP	16	25	506	13.97	11230	4.32
AM26LS32ACN.A	N	PDIP	16	25	506	13.97	11230	4.32
AM26LS32ACNG4	N	PDIP	16	25	506	13.97	11230	4.32
AM26LS32ACNG4.A	N	PDIP	16	25	506	13.97	11230	4.32
AM26LS32AIN	N	PDIP	16	25	506	13.97	11230	4.32
AM26LS32AIN.A	N	PDIP	16	25	506	13.97	11230	4.32
AM26LS32AMFKB	FK	LCCC	20	55	506.98	12.06	2030	NA
AM26LS32AMFKB.A	FK	LCCC	20	55	506.98	12.06	2030	NA
AM26LS32AMWB	W	CFP	16	25	506.98	26.16	6220	NA
AM26LS32AMWB.A	W	CFP	16	25	506.98	26.16	6220	NA
AM26LS33ACN	N	PDIP	16	25	506	13.97	11230	4.32
AM26LS33ACN.A	N	PDIP	16	25	506	13.97	11230	4.32
AM26LS33AMFKB	FK	LCCC	20	55	506.98	12.06	2030	NA
AM26LS33AMFKB.A	FK	LCCC	20	55	506.98	12.06	2030	NA
AM26LS33AMWB	W	CFP	16	25	506.98	26.16	6220	NA
AM26LS33AMWB.A	W	CFP	16	25	506.98	26.16	6220	NA

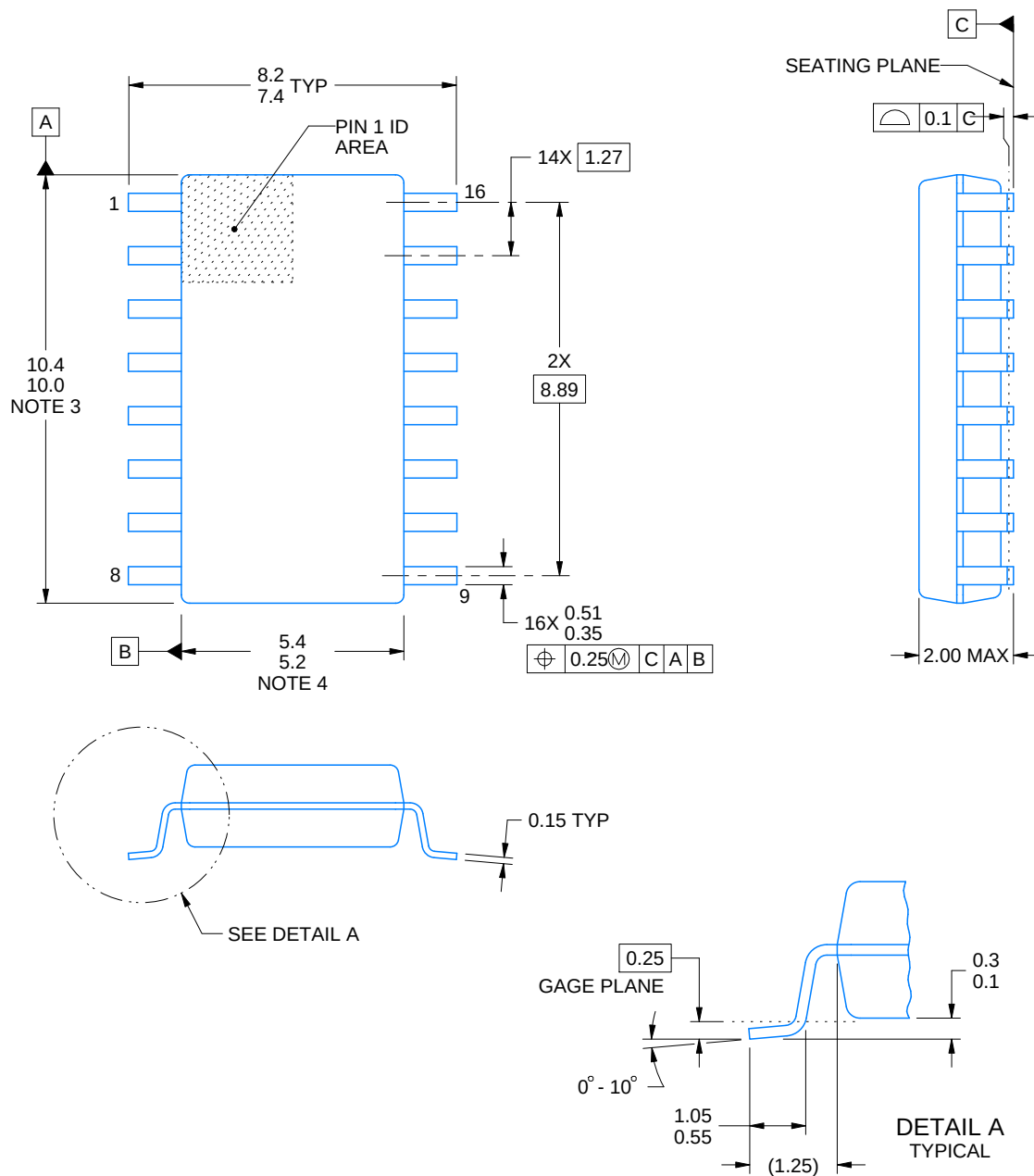


PACKAGE OUTLINE

NS0016A

SOP - 2.00 mm max height

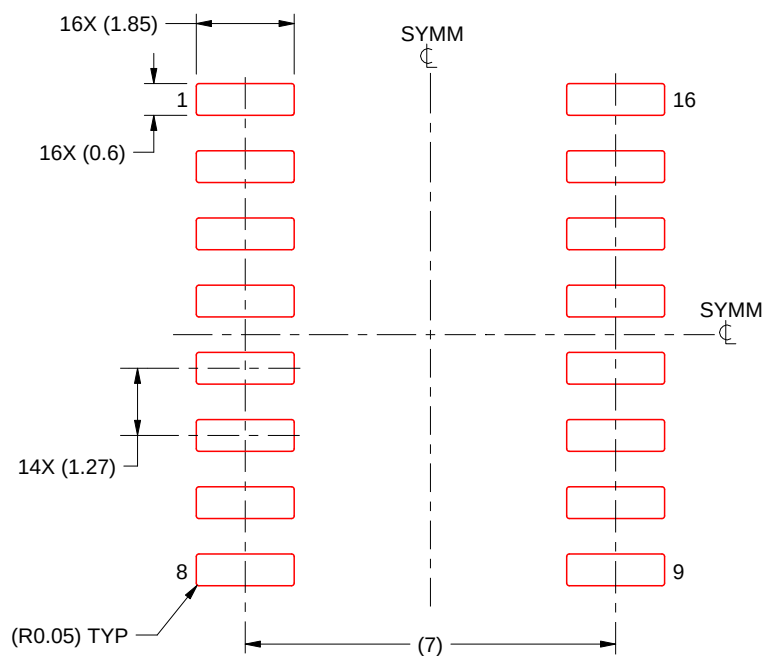
SOP



4220735/A 12/2021

NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL
 SCALE:7X

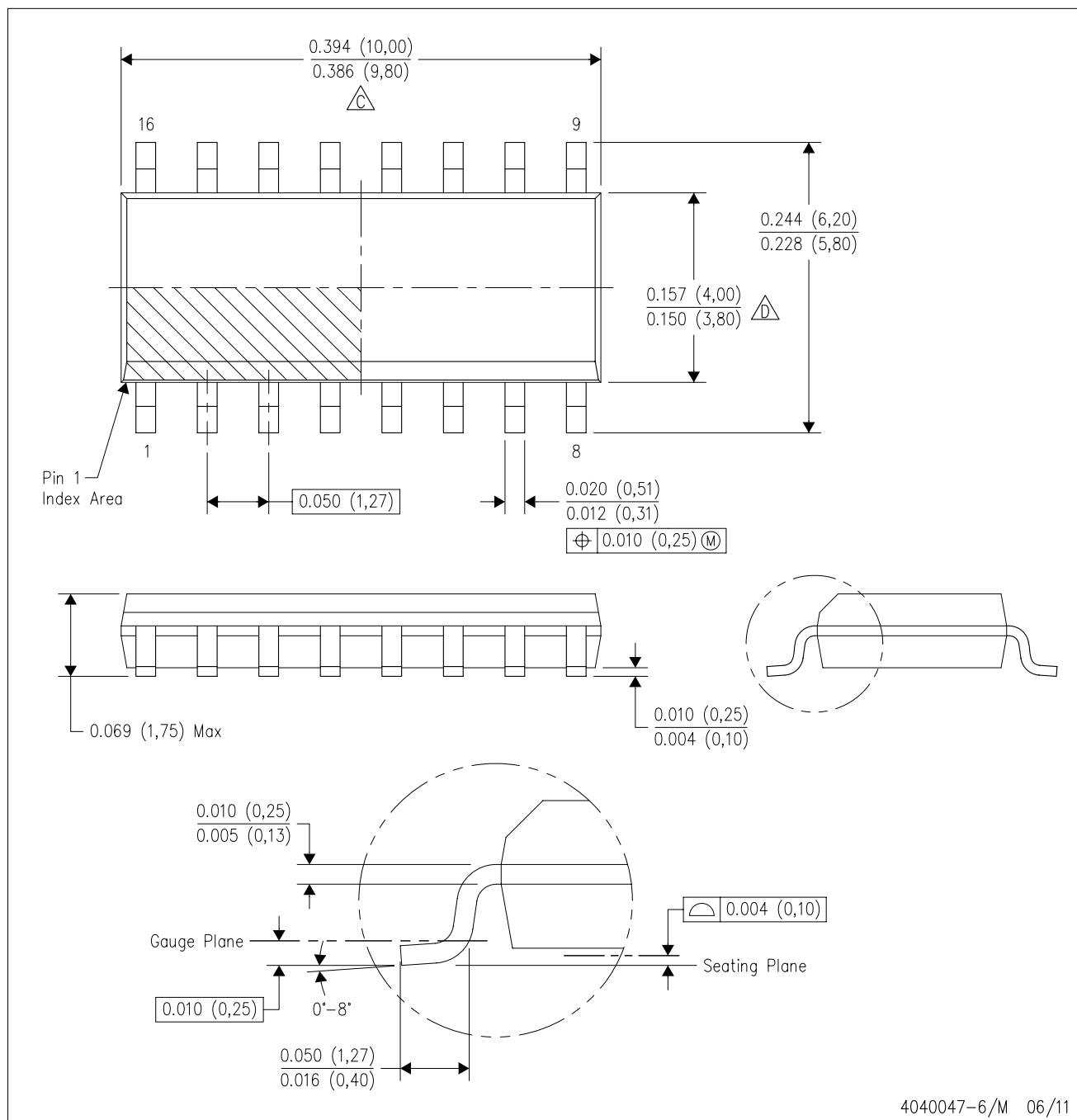
4220735/A 12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE

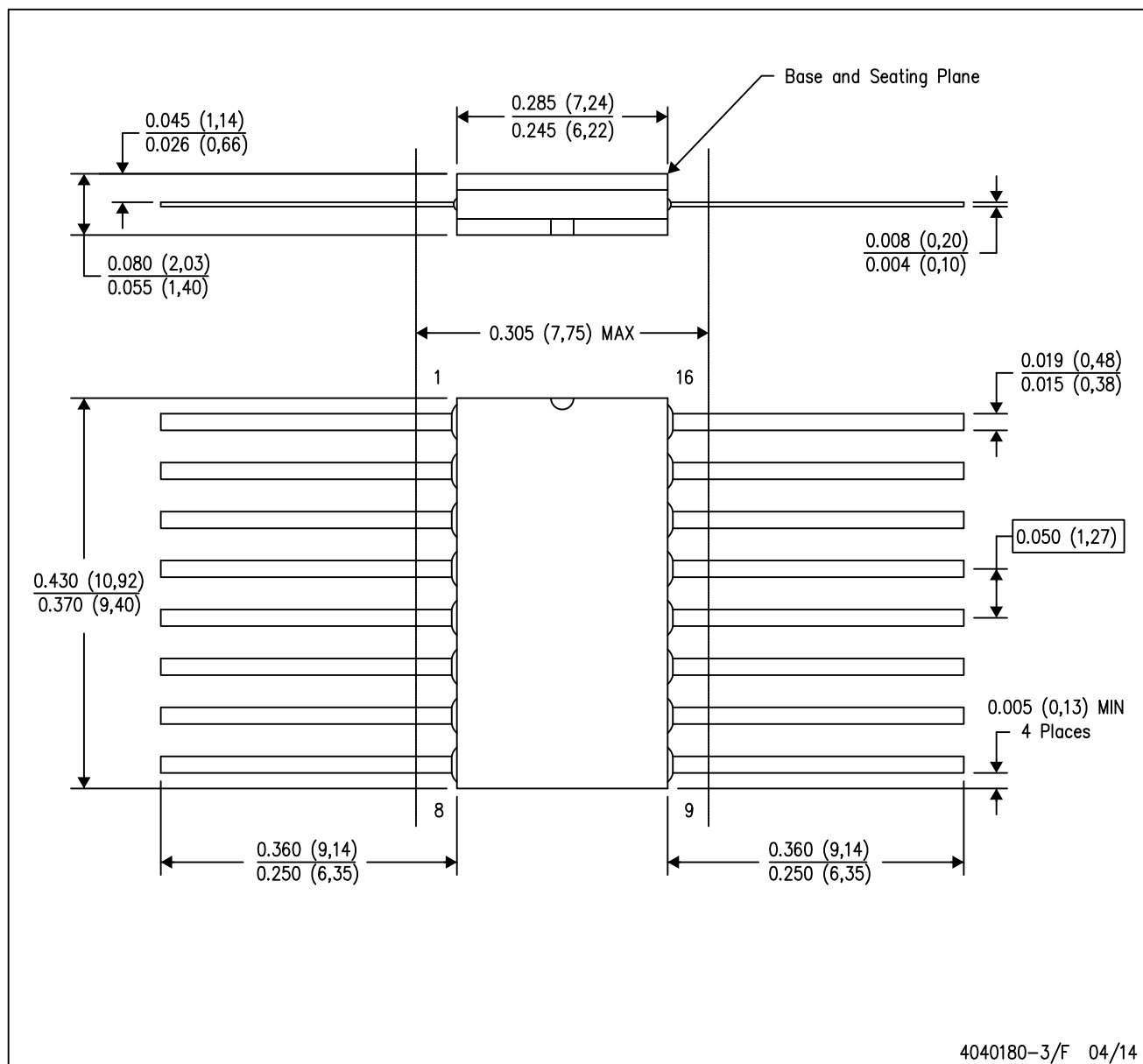


NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- This package can be hermetically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only.
- Falls within MIL STD 1835 GDFP2-F16

GENERIC PACKAGE VIEW

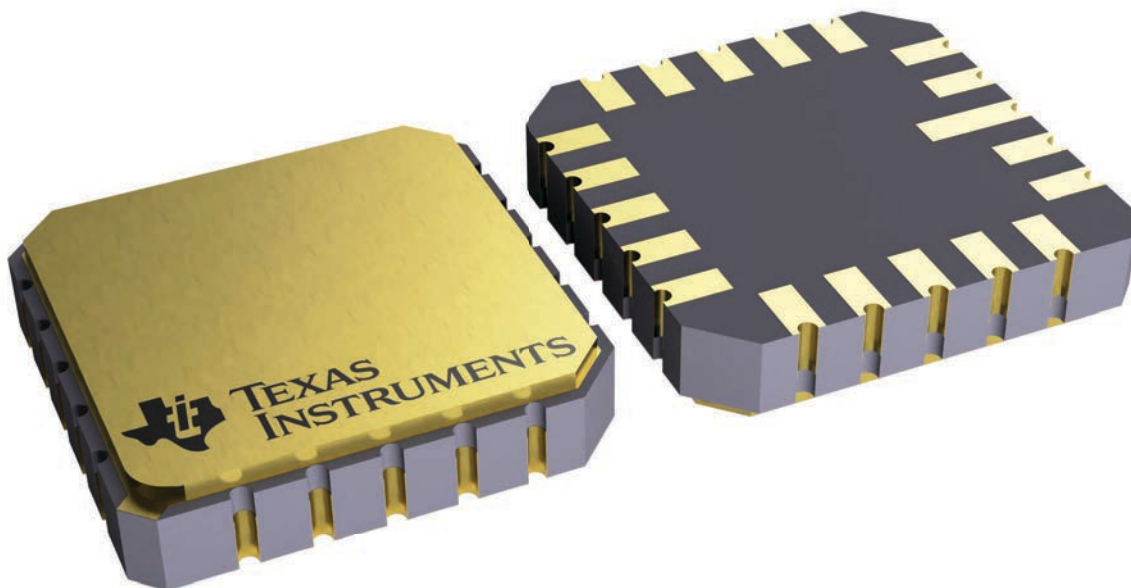
FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

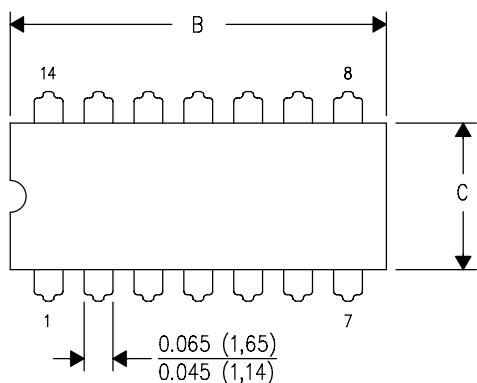


4229370VA\

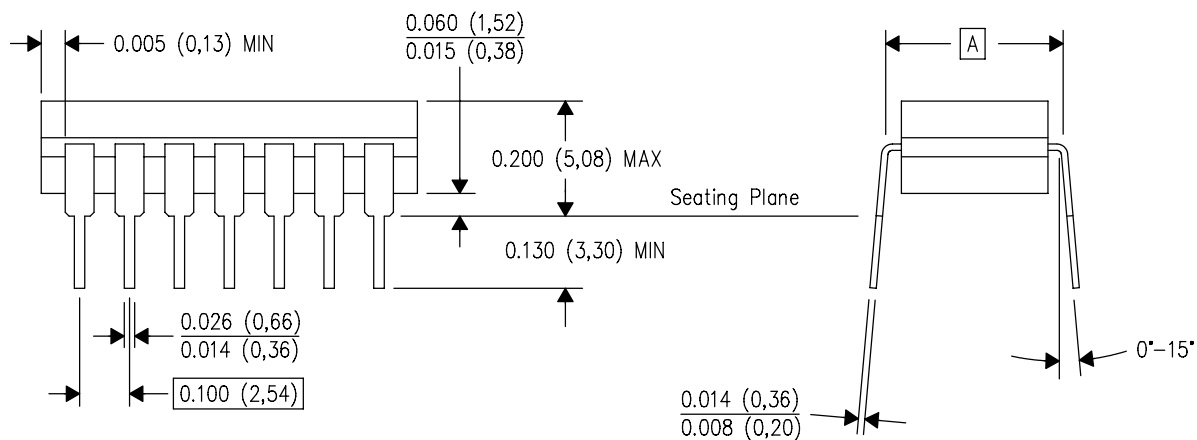
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE

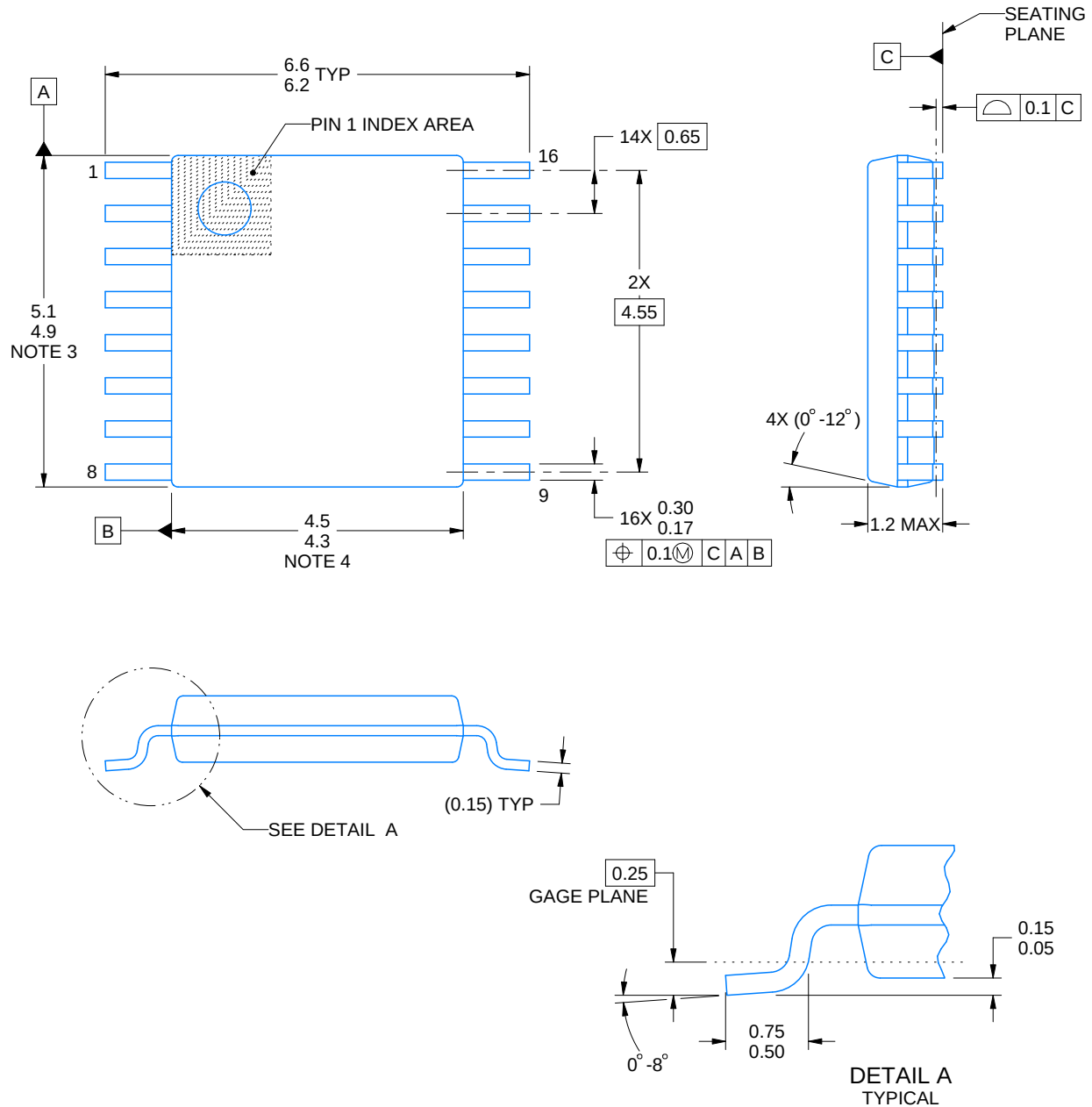
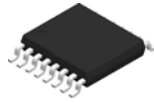


PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.



4220204/B 12/2023

NOTES:

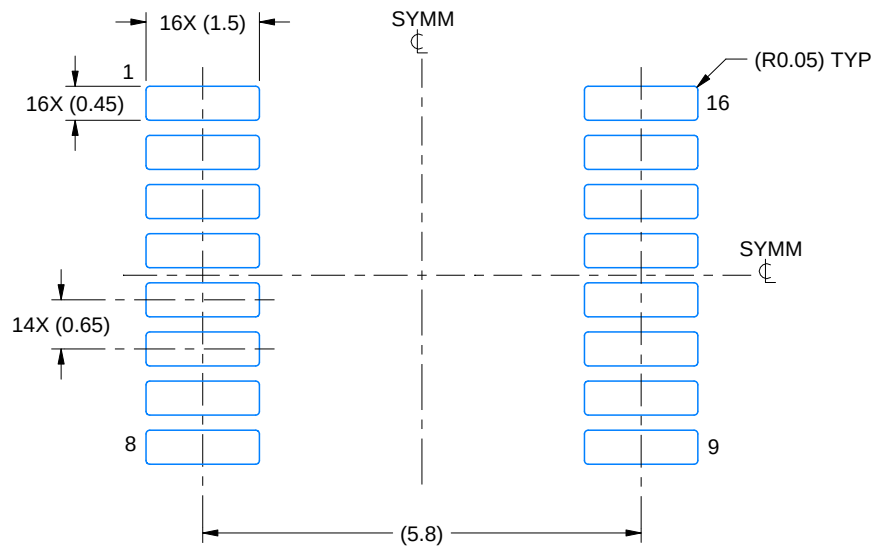
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

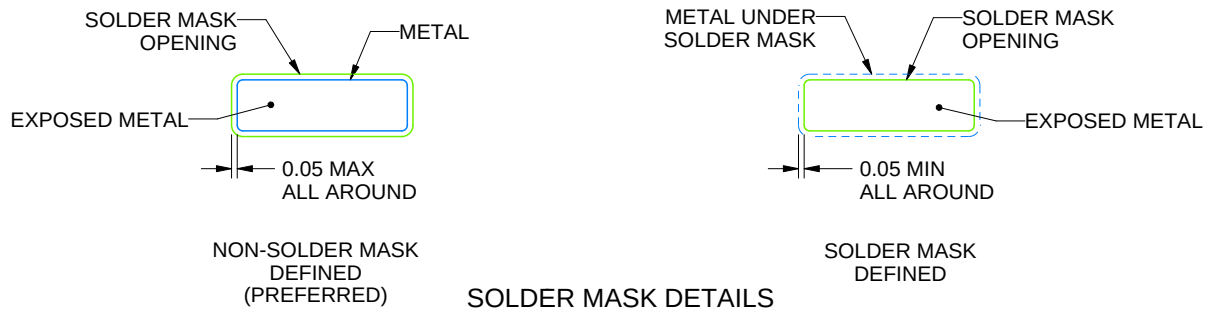
PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220204/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

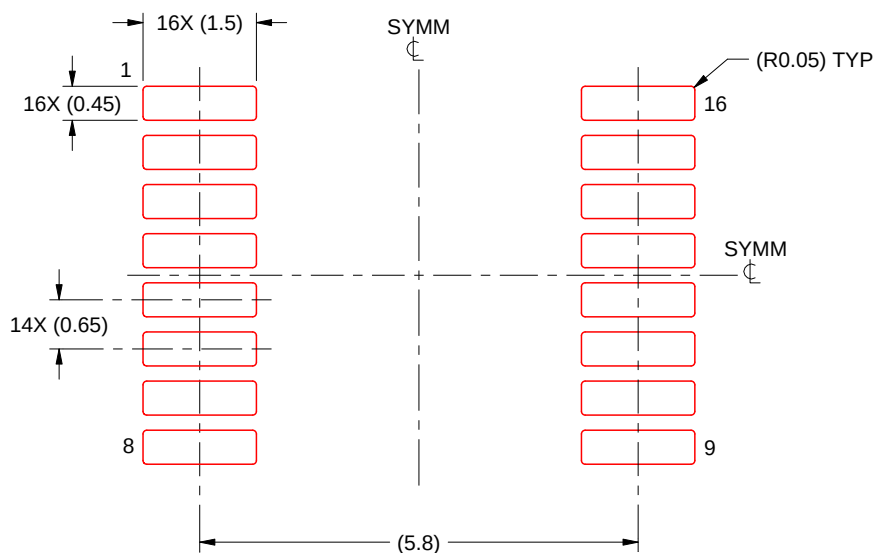
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/B 12/2023

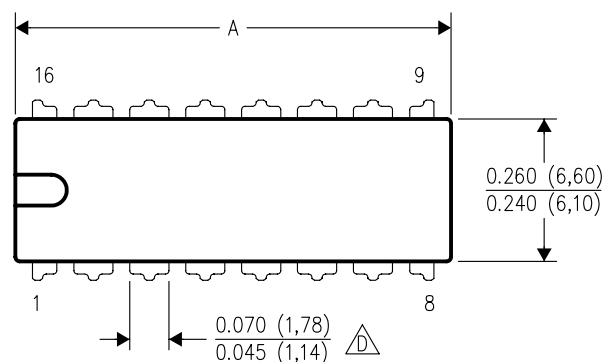
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

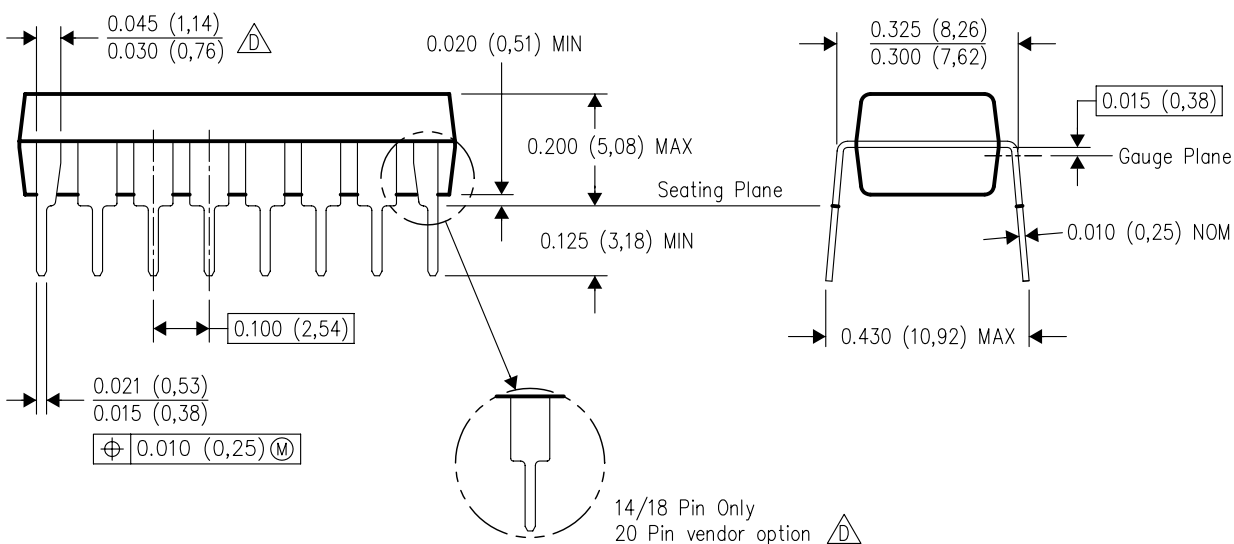
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 -  The 20 pin end lead shoulder width is a vendor option, either half or full width.

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